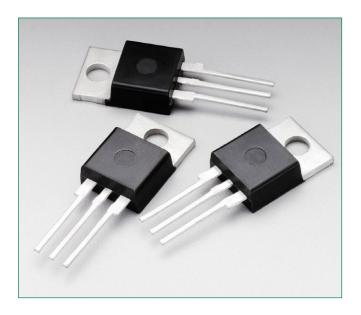


# MAC212A8, MAC212A10





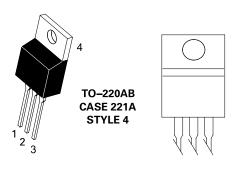
#### **Description**

Designed primarily for full-wave AC control applications, such as light dimmers, motor controls, heating controls and power supplies; or wherever full-wave silicon gate controlled solid-state devices are needed. Triac type thyristors switch from a blocking to a conducting state for either polarity of applied main terminal voltage with positive or negative gate triggering.

#### **Features**

- Blocking Voltage to 800 Volts
- All Diffused and Glass Passivated Junctions for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Construction for Low Thermal Resistance, High Heat Dissipation and Durability
- Gate Triggering Guaranteed in Four Modes (Quadrants)
- Pb-Free Packages are Available

### **Pin Out**



### **Functional Diagram**



#### **Additional Information**







Resources



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#### **Maximum Ratings** $(T_1 = 25^{\circ}C \text{ unless otherwise noted})$

Rating	Symbol	Value	Unit	
Peak Repetitive Off-State Voltage (Note 1)	MAC212A8	V <sub>DRM</sub> ,	600 800	V
(- 40 to 125°C, Sine Wave, 50 to 60 Hz, Gate Open)	MAC212A10		800	
On-State RMS Current (Full Cycle Sine Wave, 50 to 60 Hz, $T_{\rm C}$ = +85°C)		I <sub>T (RMS)</sub>	12	А
Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz, $T_{\rm c}$ = +25°C) Preceded and followed by rated current	I <sub>TSM</sub>	100	А	
Circuit Fusing Considerations (t = 8.3 ms)	l²t	40	A²sec	
Peak Gate Power ( $T_c = +85^{\circ}\text{C}$ , Pulse Width = 10 $\mu$ s)	P <sub>GM</sub>	20	W	
Average Gate Power (t = 8.3 ms, $T_C = +85^{\circ}C$ )	P <sub>G (AV)</sub>	0.35	W	
Peak Gate Current ( $T_c = +85^{\circ}$ C, Pulse Width = 10 µs)	I <sub>GM</sub>	2.0	А	
Operating Junction Temperature Range	T <sub>J</sub>	-40 to +125	°C	
Storage Temperature Range	T <sub>stg</sub>	-40 to +150	°C	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are

#### **Thermal Characteristics**

Rating		Symbol	Value	Unit
Thermal Resistance,	Junction-to-Case (AC) Junction-to-Ambient	R <sub>ejc</sub> R <sub>eja</sub>	2.0 62.5	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds		$T_L$	260	°C

### Electrical Characteristics - OFF (T, = 25°C unless otherwise noted; Electricals apply in both directions)

Characteristic		Symbol	Min	Тур	Max	Unit
Peak Repetitive Blocking Current	T, = 25°C	I <sub>DRM</sub> ,	-	-	1.0	A
$(V_D = V_{DRM} = V_{RRM}; Gate Open)$	$T_J = 125^{\circ}C$	I <sub>RRM</sub>	-	-	2.0	mA mA

### Electrical Characteristics - ON (T<sub>x</sub> = 25°C unless otherwise noted; Electricals apply in both directions)

Characteristic			Min	Тур	Max	Unit
Peak On-State Voltage (TM = 14 A Peak; Pulse Width = 1 to 2 n	ns, Duty Cycle 2%)	$V_{TM}$	-	1.3	1.75	V
	MT2(+), G(+)		-	12	50	
Gate Trigger Current (Continuous dc)	MT2(+), G(-)		-	12	50	, A
(Main Terminal Voltage = 12 Vdc, $R_L = 100 \Omega$ )	MT2(-), G(-)	GT	-	20	50	mA
	MT2(-), G(+)		-	35	75	
	MT2(+), G(+)	V <sub>GT</sub>	-	0.9	2.0	
Gate Trigger Voltage (Continuous dc)	MT2(+), G(-)		-	0.9	2.0	V
(Main Terminal Voltage = 12 Vdc, $R_L = 100 \Omega$ )	MT2(-), G(-)		-	1.1	2.0	V
	MT2(-), G(+)		-	1.4	2.5	
Gate Non-Trigger Voltage (Continuous dc) (Main Terminal Voltage = 12 Vdc, $R_L$ = 100 $\Omega$ ) All Four Quadrants			0.02	_	_	V
Holding Current (Main Terminal Voltage = 12 Vdc, Gate Open, Initiating Current = $\pm$ 200 mA)		I <sub>H</sub>	-	6.0	50	mA
Turn-On Time (Rated $V_{DRM'}$ $I_{TM}$ = 17 A) ( $I_{GT}$ = 120 mA, Rise Time = 0.1 µs, Pulse Width = 2 µs)		t <sub>gt</sub>	-	1.5	_	μs

not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

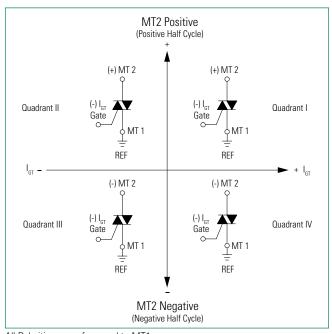


Dynamic Characteristics					
Characteristic	Symbol	Min	Тур	Max	Unit
Critical Rate of Rise of Commutation Voltage ( $V_D = Rated V_{DRM}$ , $I_{TM} = 11.3$ A, Commutating di/dt = 6.1 A/ms, Gate Unenergized, $T_C = +85^{\circ}\text{C}$ )		_	5.0	-	A/ms
Critical Rate of Rise of Off-State Voltage $(V_D = Rated V_{DRM'} Exponential Waveform, Gate Open, T_C = +85°C)$		_	100	-	V/µs

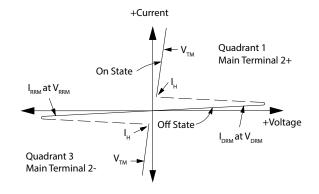
# **Voltage Current Characteristic of SCR**

Symbol	Parameter
V <sub>DRM</sub>	Peak Repetitive Forward Off State Voltage
I <sub>DRM</sub>	Peak Forward Blocking Current
V <sub>RRM</sub>	Peak Repetitive Reverse Off State Voltage
I <sub>RRM</sub>	Peak Reverse Blocking Current
V <sub>TM</sub>	Maximum On State Voltage
I <sub>H</sub>	Holding Current

#### **Quadrant Definitions for a Triac**



All Polarities are referenced to MT1. With in-phase signals (using standard AC lines) quadrants I and III are used







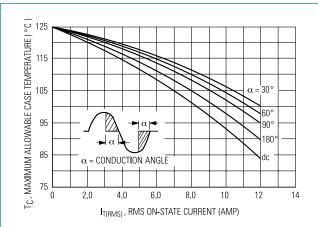


Figure 3. Maximum On-State Characteristics

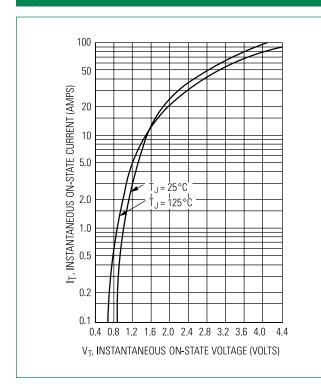


Figure 2. Power Dissipation

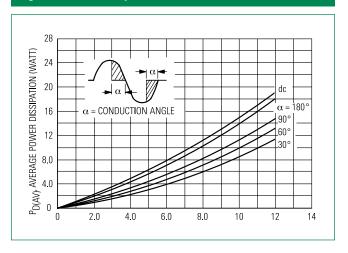


Figure 4. Maximum Non-Repetitive Surge Current

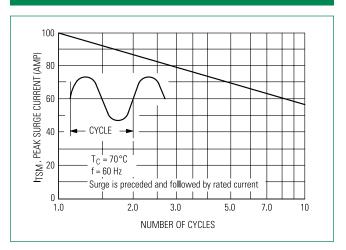
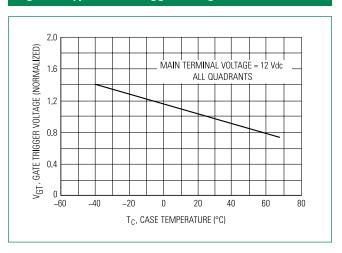
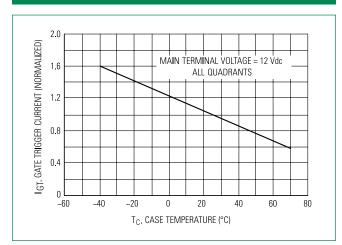


Figure 5. Typical Gate Trigger Voltage

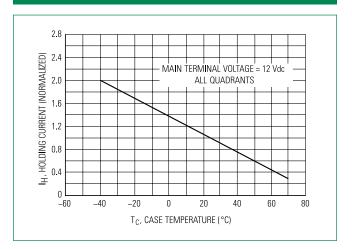




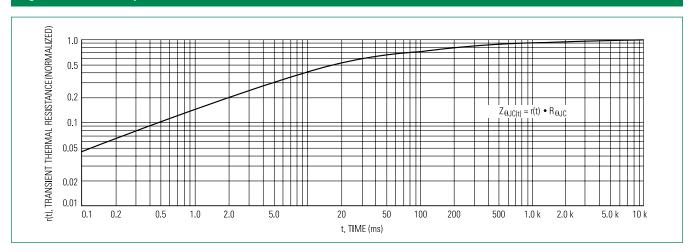
# Figure 6. Typical Gate Trigger Current



# Figure 7. Typical Holding Current

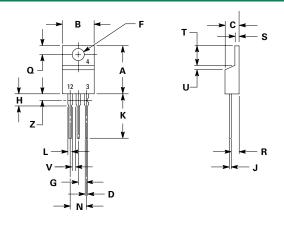


# Figure 8. Thermal Response

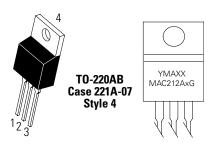




#### **Dimensions**



# **Part Marking System**



=8 or 10 =Year =Month =Assembly Site =Lot Serial Code A XX =Pb-Free Package

Dis.	Inches		Millin	neters
Dim	Min	Max	Min	Max
Α	0.590	0.620	14.99	15.75
В	0.380	0.420	9.65	10.67
С	0.178	0.188	4.52	4.78
D	0.025	0.035	0.64	0.89
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.41	2.67
Н	0.110	0.130	2.79	3.30
J	0.018	0.024	0.46	0.61
K	0.540	0.575	13.72	14.61
L	0.060	0.075	1.52	1.91
N	0.195	0.205	4.95	5.21
Q	0.105	0.115	2.67	2.92
R	0.085	0.095	2.16	2.41
S	0.045	0.060	1.14	1.52
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

Pin Assignment			
1	Cathode		
2	Anode		
3	Gate		
4	Anode		

Ordering Information		
Device	Package	Shipping
MAC212A8	TO-220AB	
MAC212A8G	TO-220AB (Pb-Free)	500
MAC212A10	TO-220AB	Units/ Box
MAC212A10G	TO-220AB (Pb-Free)	

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE

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